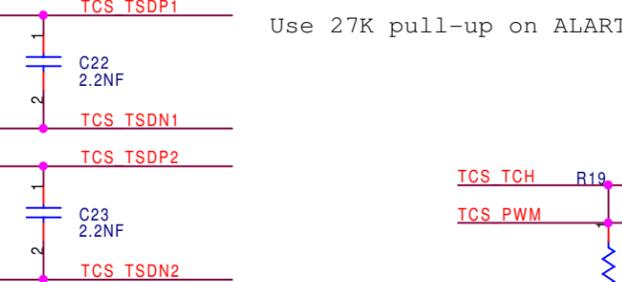


Required to limit power

USE RESISTOR TO REDUCE XTAL DRIVE POWER TO 50 uW IF NECESSARY. OTHERWISE USE 0 OHM RESISTOR.

VDD1P05	4	VDDIO_25MA	8	TCSR24M	R23	1	2	39	TCS 24M
3P3VDD24M	7	VDD_24M	28	TCSR32KB	R24	1	2	39	TCS 32KB
3P3VDD27M	10	VDD_27M	9	TCSR27M	R25	1	2	39	TCS 27M
3P3VDD25MB	13	VDD_25MB	6	TCSR25MA	R21	1	2	0	TCS 25MA
3P3VDD3P3	21	V_3.3	11	TCSR25MB	R22	1	2	0	TCS 25MB
3P3VDD32KA	22	VDD_RTC_OUT	3	TCSR32KA	R10	1	2	0	TCS 32KA
3P3VDDTS	26	VDD_TS	23	TCS_ALERT#					
3P3VDD32KB	29	VDD_32KB	24	TCS_FLT#					
TCS_VBAT	30	VBAT	16	TCS_PWM					
			5	GND					
			12	GND					
			27	GND					
			25	GND					
			33	THERMAL PAD					
			34	THERMAL PAD					
			35	THERMAL PAD					
			36	THERMAL PAD					
				9TCS1083					

Do not use multiple pull-up resistors on SMBus signals.
Use 27K pull-up on ALERT#



- Layout notes.
1. Separate Xout and Xin in traces by 3 x the trace width.
 2. Do not share crystal load capacitor ground via with other components.
 3. Ground C10 and C11 to U1 pin 29.
 4. Route power from bead through bulk capacitor pad then through 0.1 uF capacitor pad then to clock chip Vdd pad.
 5. Do not share ground vias. One ground one ground via.

NOTE:FERRITE BEADS =

Manufacture	Part Number	Z@100MHz	PkgSz	DC res.	Current (Ma)
muRata	BLM21A601R	600	0805	0.30	600
TDK	MMZ2012S601A	600	0805	0.30	600
STEWART	HZ0805E601R	600	0805	0.30	600
AssocCmpTch	CBG0805-600-50	600	0805	0.30	600

Manufacture	Part Number	Z@100MHz	PkgSz	DC res.	Current (Ma)
muRata	BLM18AG601SN1	600	0603	0.50	200
muRata	BLM18BD601SN1_PB	600	0603	0.65	200
Ceratech	HB-1T1608-601	600	0603	0.50	200
TDK	MMZ1608R301A	300	0603	0.20	500

Integrated Device Technology
San Jose, CA

Title: REFERENCE SCHEMATIC

Size B | Document Number: 9TCS1083 | Rev: 0.3

Date: Tuesday, October 04, 2011 | Sheet: 1 of 1